

PHOTOCOUPLER

PS2501-1,-2,-4,PS2501L-1,-2,-4

HIGH ISOLATION VOLTAGE SINGLE TRANSISTOR TYPE MULTI PHOTOCOUPLER SERIES

-NEPOC Series-

DESCRIPTION

The PS2501-1, -2, -4 and PS2501L-1, -2, -4 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon phototransistor.

The PS2501-1, -2, -4 are in a plastic DIP (Dual In-line Package) and the PS2501L-1, -2, -4 are lead bending type (Gull-wing) for surface mount.

FEATURES

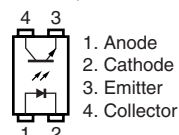
- High isolation voltage ($BV = 5\,000\text{ V r.m.s.}$)
- High collector to emitter voltage ($V_{CEO} = 80\text{ V}$)
- High-speed switching ($t_r = 3\text{ }\mu\text{s TYP.}$, $t_f = 5\text{ }\mu\text{s TYP.}$)
- Ordering number of tape product: PS2501L-1-E3, E4, F3, F4, PS2501L-2-E3, E4
- Safety standards
 - UL approved: File No. E72422

APPLICATIONS

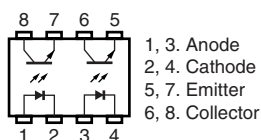
- Power supply
- Telephone/FAX.
- FA/OA equipment
- Programmable logic controller

PIN CONNECTION (Top View)

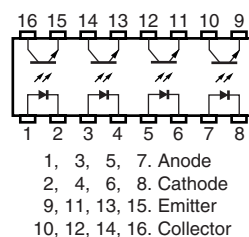
PS2501-1, PS2501L-1



PS2501-2, PS2501L-2



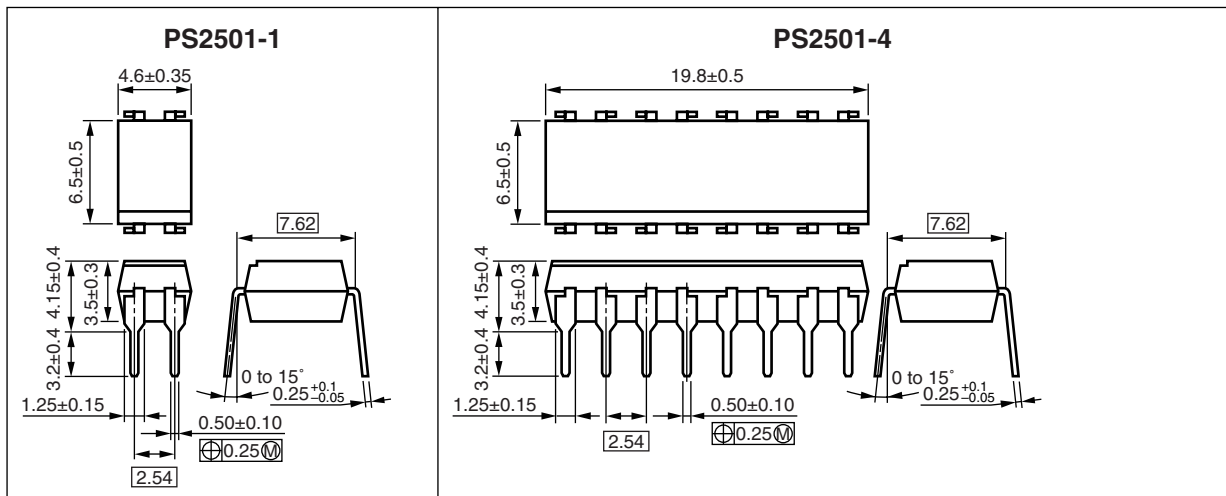
PS2501-4, PS2501L-4



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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

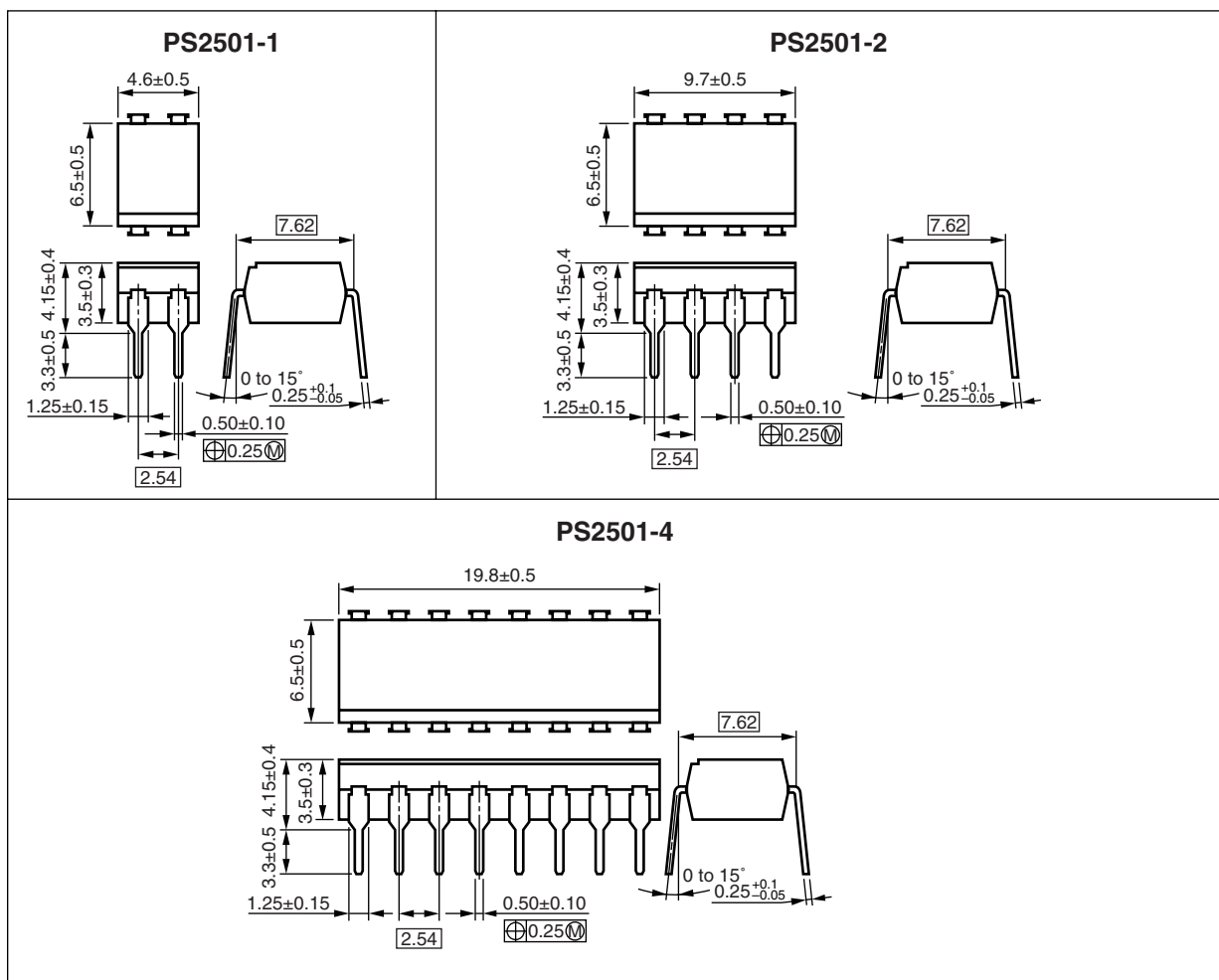
PACKAGE DIMENSIONS (UNIT : mm)

DIP Type (New package)

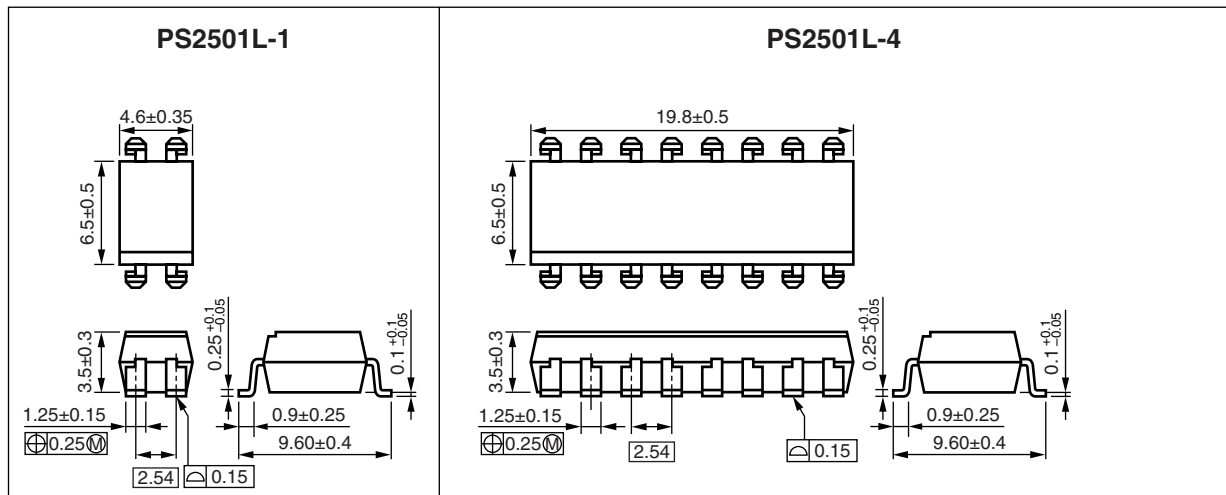


Caution New package 1-ch, 4-ch only

DIP Type

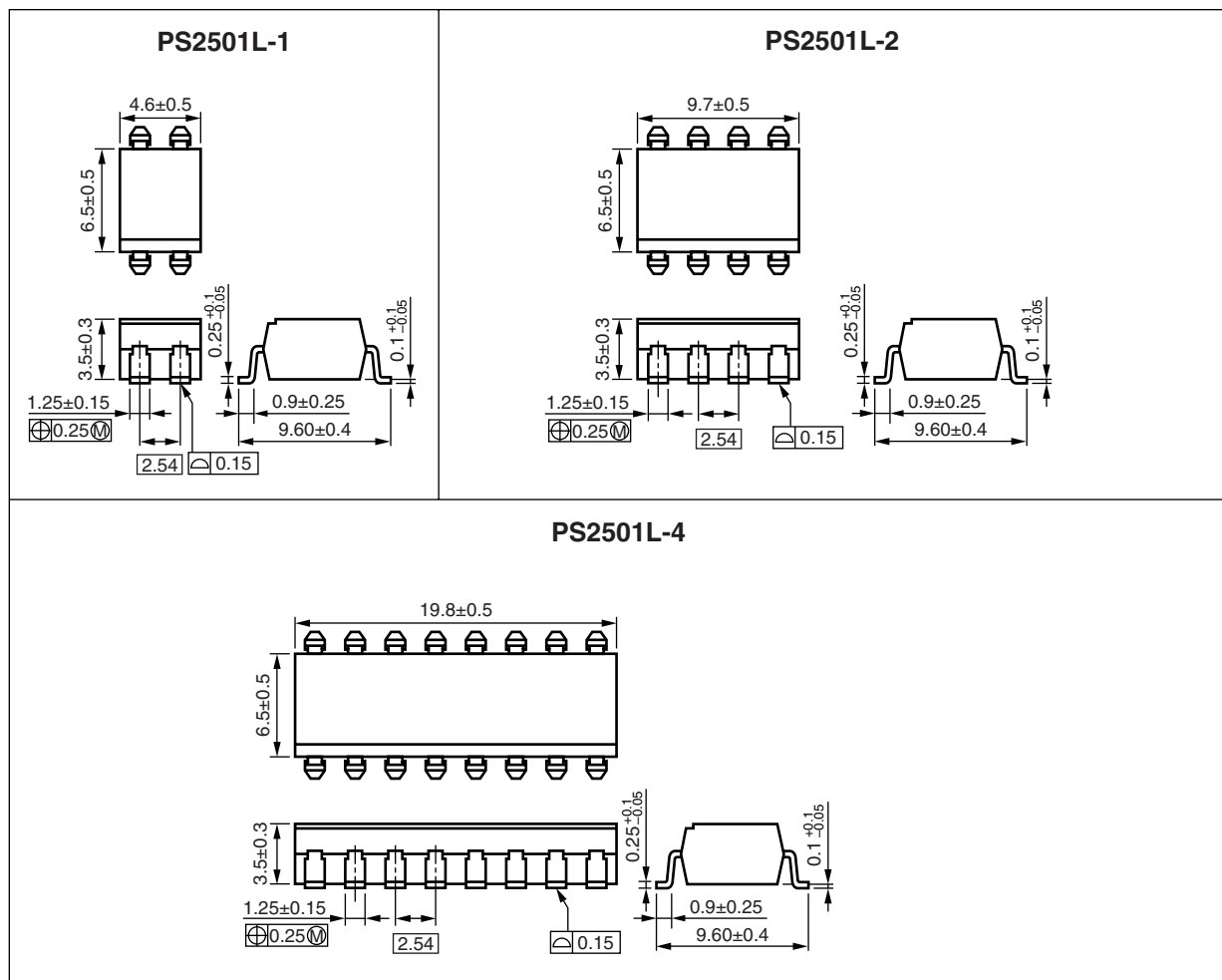


Lead Bending Type (New package)

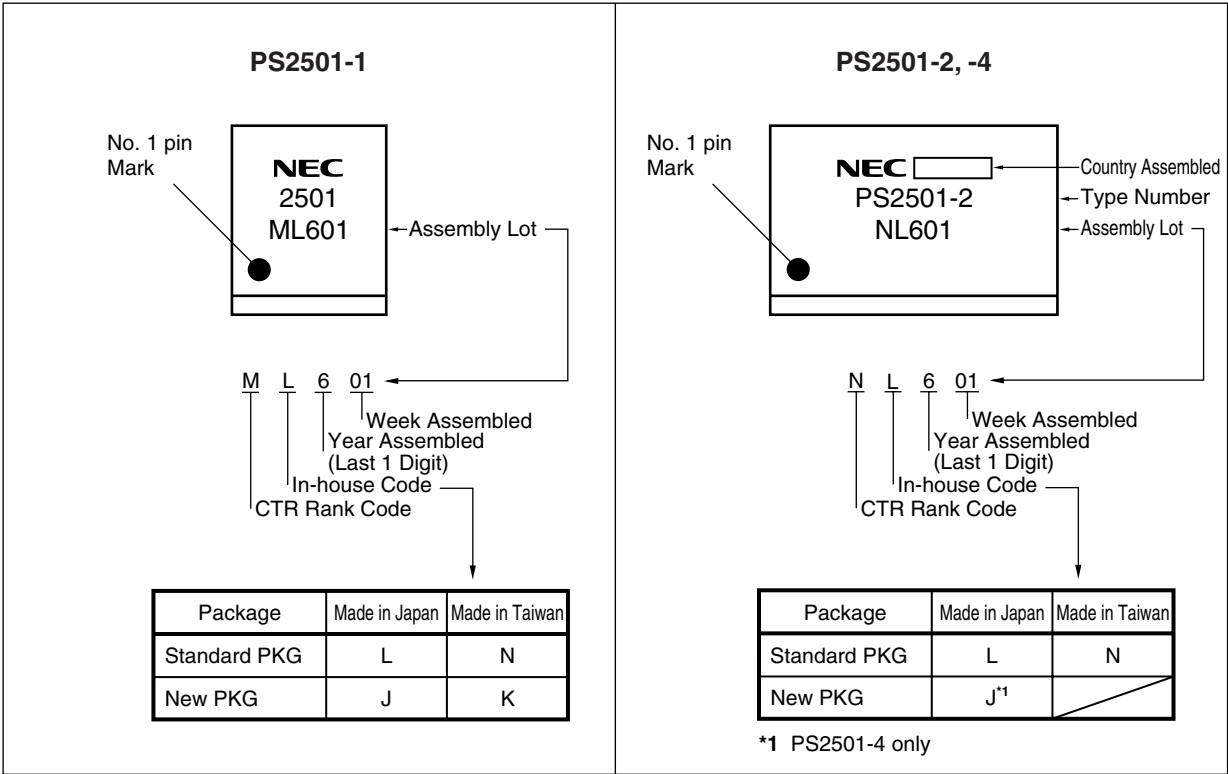


Caution New package 1-ch, 4-ch only

Lead Bending Type



★ MARKING EXAMPLE



★ ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}
PS2501-1	PS2501-1-A	Pb-Free	Magazine case 100 pcs	Standard products (UL approved)	PS2501-1
PS2501L-1	PS2501L-1-A				
PS2501L-1-E3	PS2501L-1-E3-A		Embossed Tape 1 000 pcs/reel		
PS2501L-1-E4	PS2501L-1-E4-A				
PS2501L-1-F3	PS2501L-1-F3-A		Embossed Tape 2 000 pcs/reel		
PS2501L-1-F4	PS2501L-1-F4-A				
PS2501-2	PS2501-2-A		Magazine case 45 pcs		PS2501-2
PS2501L-2	PS2501L-2-A				
PS2501L-2-E3	PS2501L-2-E3-A		Embossed Tape 1 000 pcs/reel		
PS2501L-2-E4	PS2501L-2-E4-A				PS2501-4
PS2501-4	PS2501-4-A		Magazine case 20 pcs		
PS2501L-4	PS2501L-4-A				

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (Unless otherwise specified, T_A = 25°C)

Parameter		Symbol	Ratings		Unit
			PS2501-1, PS2501L-1	PS2501-2,-4 PS2501L-2,-4	
Diode	Reverse Voltage	V _R	6		V
	Forward Current (DC)	I _F	80		mA/ch
	Power Dissipation Derating	ΔP _D /°C	1.5	1.2	mW/°C
	Power Dissipation	P _D	150	120	mW/ch
	Peak Forward Current ^{*1}	I _{FP}	1		A/ch
Transistor	Collector to Emitter Voltage	V _{CEO}	80		V
	Emitter to Collector Voltage	V _{ECO}	7		V
	Collector Current	I _C	50		mA/ch
	Power Dissipation Derating	ΔP _C /°C	1.5	1.2	mW/°C
	Power Dissipation	P _C	150	120	mW/ch
Isolation Voltage ^{*2}		BV	5 000		Vr.m.s.
Operating Ambient Temperature		T _A	-55 to +100		°C
Storage Temperature		T _{stg}	-55 to +150		°C

*1 PW = 100 μs, Duty Cycle = 1%

*2 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output.

Pins 1-2 shorted together, 3-4 shorted together (PS2501-1, PS2501L-1).

Pins 1-4 shorted together, 5-8 shorted together (PS2501-2, PS2501L-2).

Pins 1-8 shorted together, 9-16 shorted together (PS2501-4, PS2501L-4).

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 10 mA		1.17	1.4	V
	Reverse Current	I _R	V _R = 5 V			5	μA
	Terminal Capacitance	C _t	V = 0 V, f = 1.0 MHz		50		pF
Transistor	Collector to Emitter Dark Current	I _{CEO}	V _{CE} = 80 V, I _F = 0 mA			100	nA
Coupled	Current Transfer Ratio (I _C /I _F) ^{*1}	CTR	I _F = 5 mA, V _{CE} = 5 V	80	300	600	%
	Collector Saturation Voltage	V _{CE(sat)}	I _F = 10 mA, I _C = 2 mA			0.3	V
	Isolation Resistance	R _{I-O}	V _{I-O} = 1.0 kV _{DC}	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1.0 MHz		0.5		pF
	Rise Time ^{*2}	t _r	V _{CC} = 10 V, I _C = 2 mA, R _L = 100 Ω		3		μs
	Fall Time ^{*2}	t _f			5		

***1** CTR rank (* : only PS2501-1, PS2501L-1)

K* : 300 to 600 (%)

L* : 200 to 400 (%)

M* : 80 to 240 (%)

D* : 100 to 300 (%)

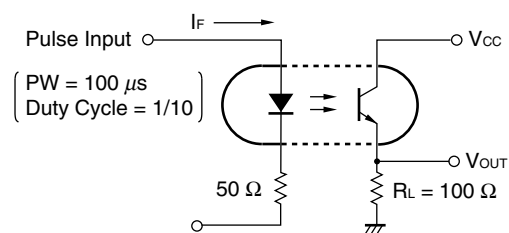
H* : 80 to 160 (%)

W* : 130 to 260 (%)

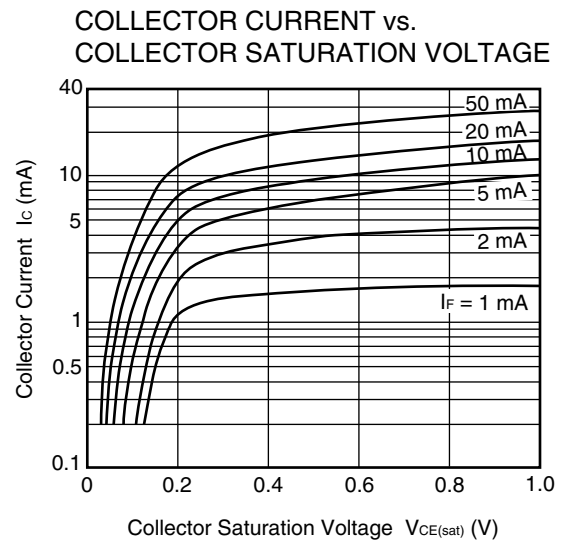
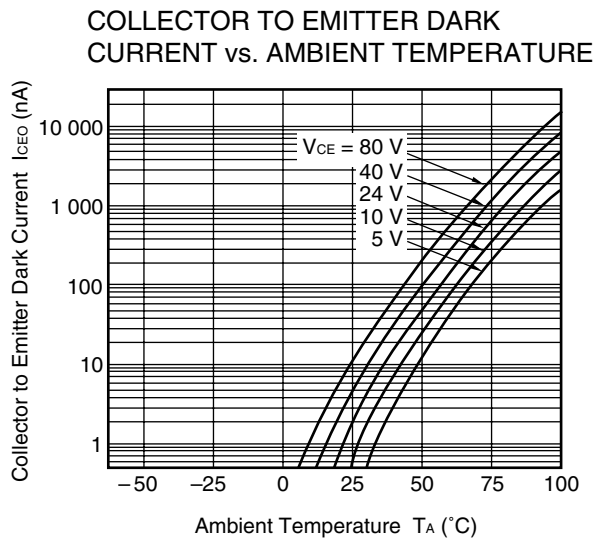
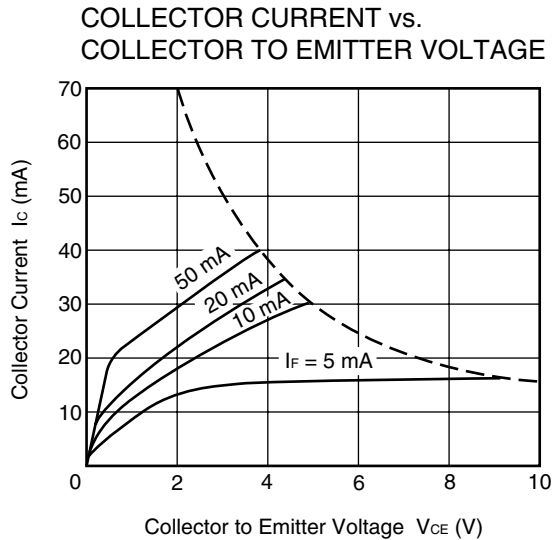
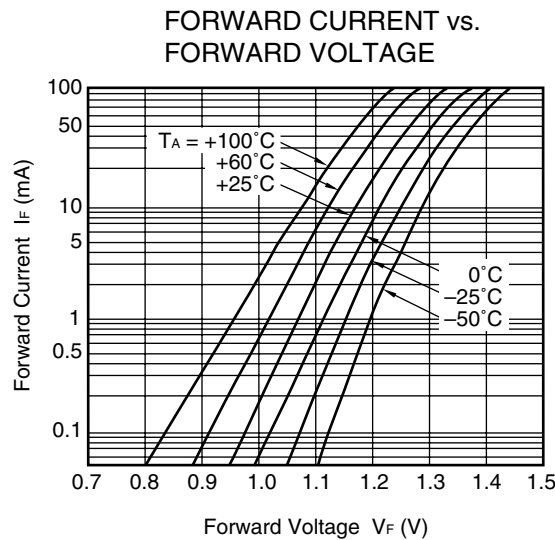
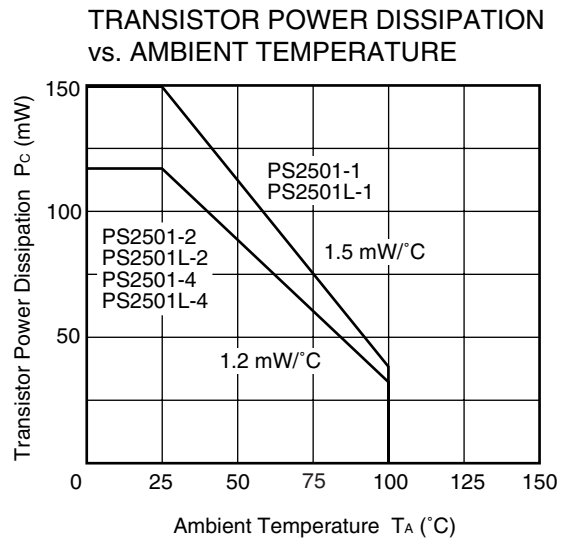
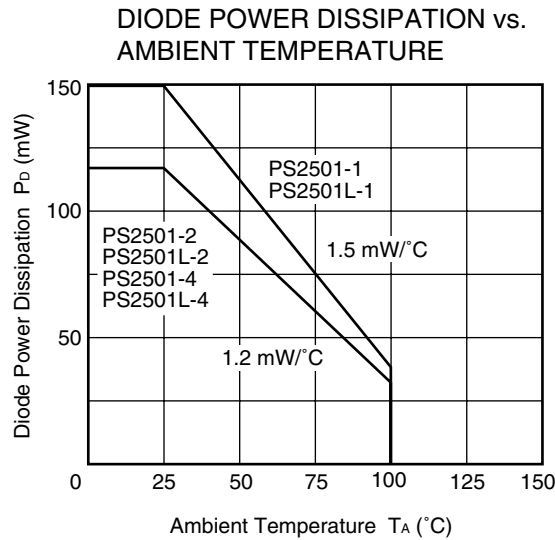
Q* : 100 to 200 (%)

N : 80 to 600 (%)

***2** Test circuit for switching time

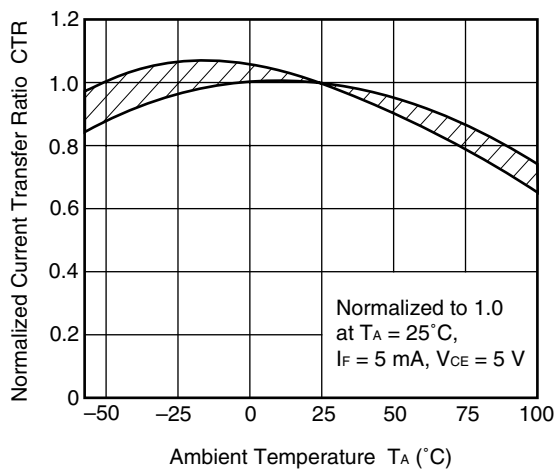


TYPICAL CHARACTERISTICS (Unless otherwise specified, $T_A = 25^\circ\text{C}$)

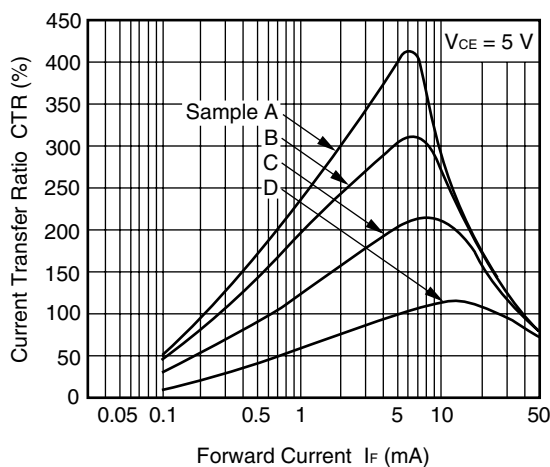


Remark The graphs indicate nominal characteristics.

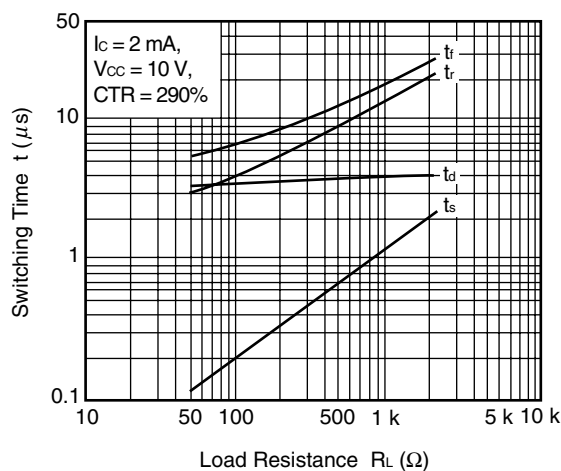
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



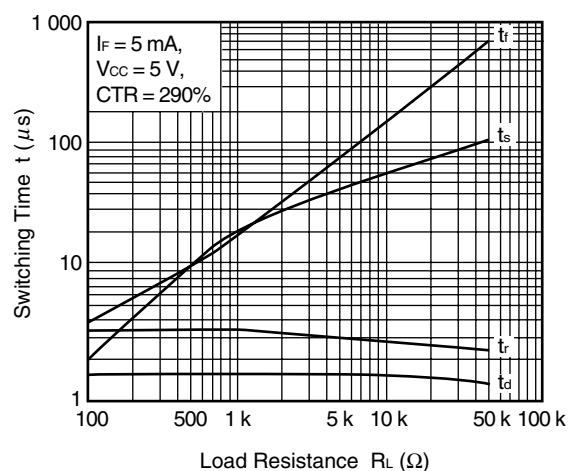
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



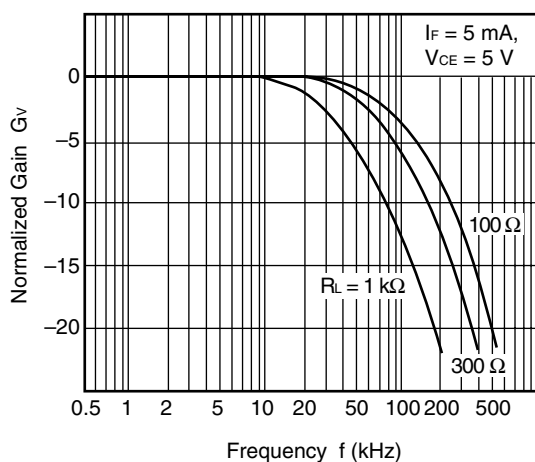
SWITCHING TIME vs. LOAD RESISTANCE



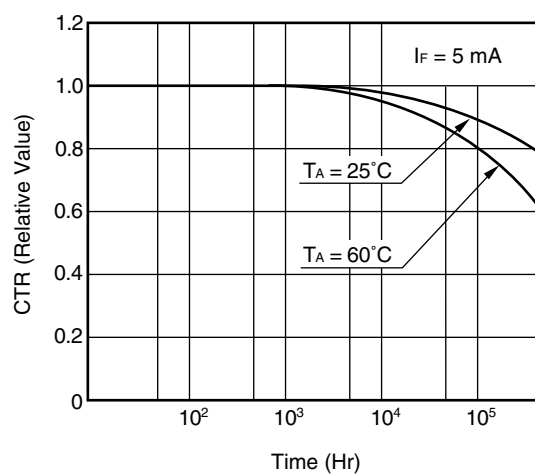
SWITCHING TIME vs. LOAD RESISTANCE



FREQUENCY RESPONSE



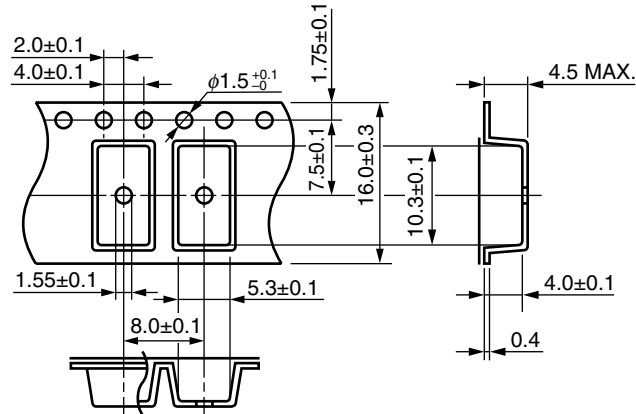
LONG TERM CTR DEGRADATION



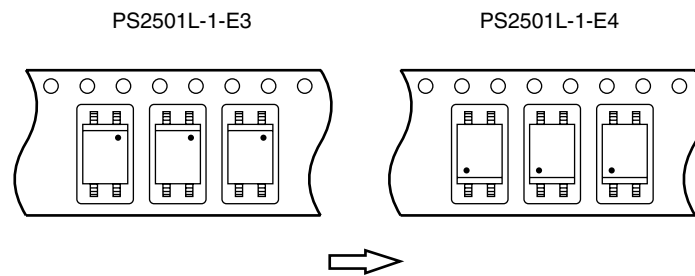
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT : mm)

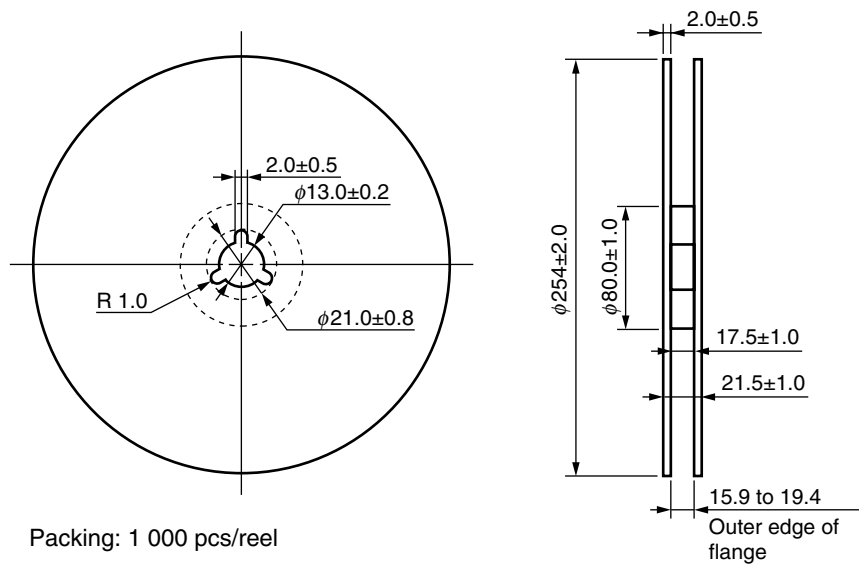
Outline and Dimensions (Tape)



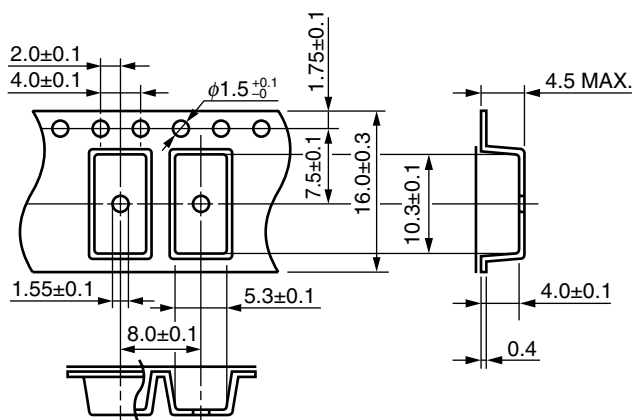
Tape Direction



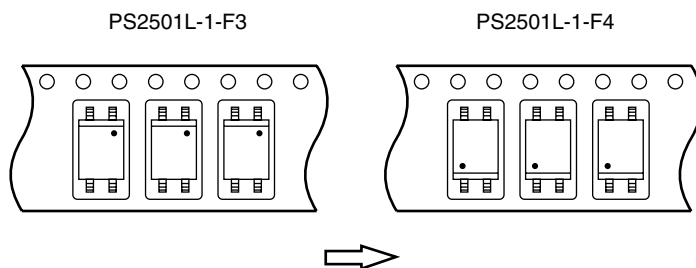
Outline and Dimensions (Reel)



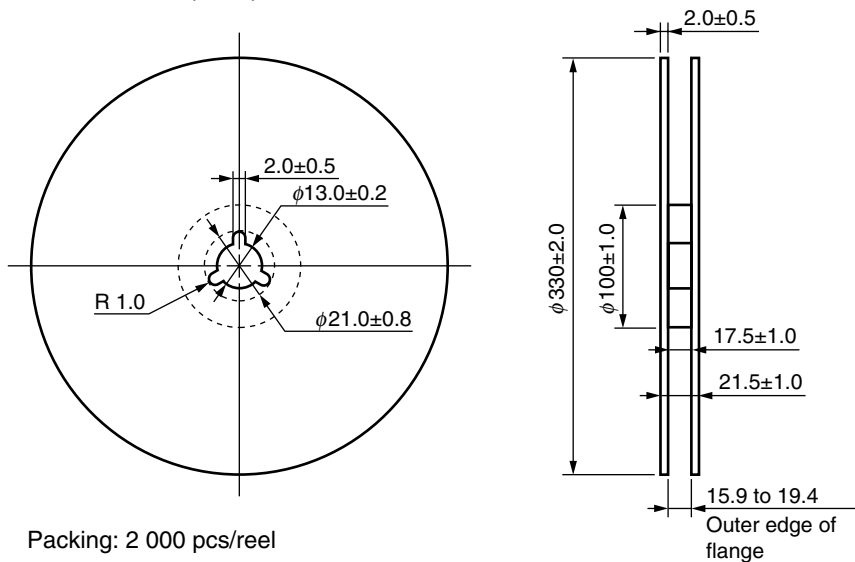
Outline and Dimensions (Tape)



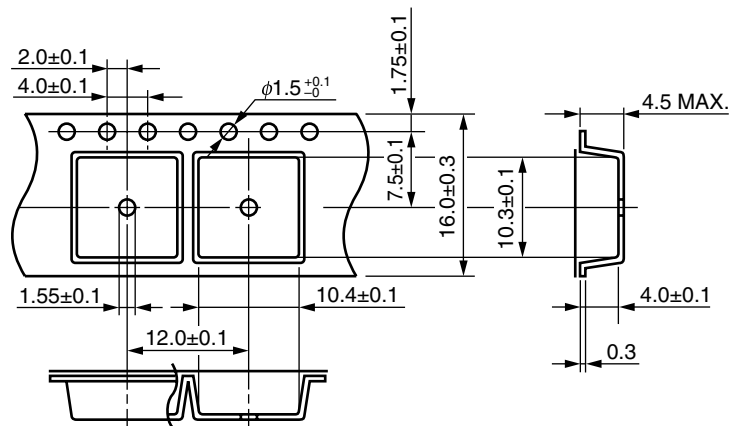
Tape Direction



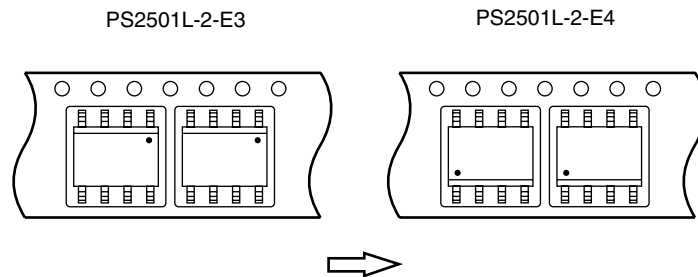
Outline and Dimensions (Reel)



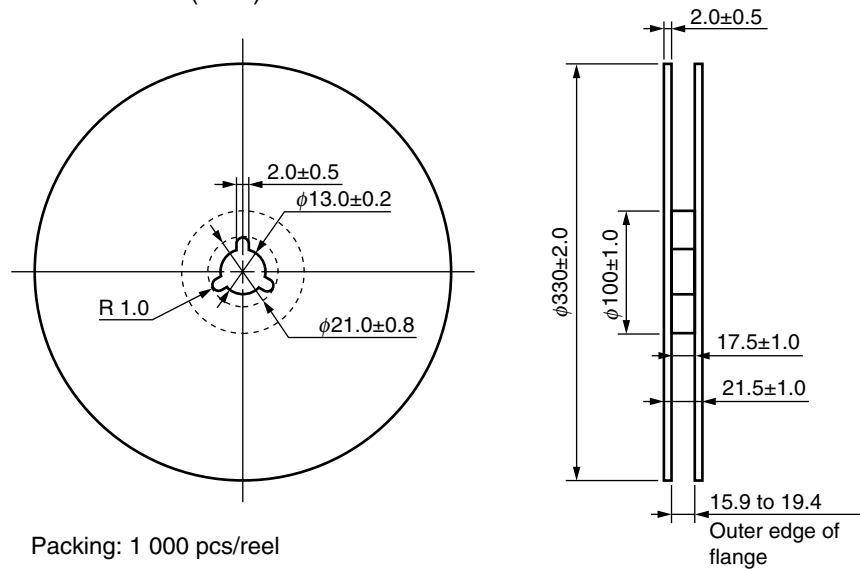
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



Packing: 1 000 pcs/reel

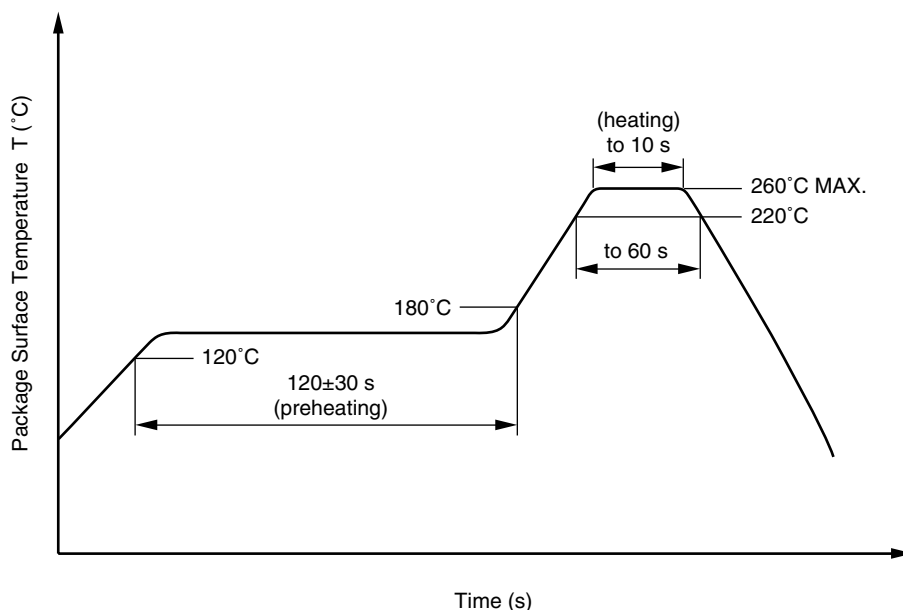
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by soldering iron

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

★ 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. This tendency may sometimes be obvious, especially below $I_F = 1 \text{ mA}$.

Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

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M8E 00.4-0110

Caution	GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points. • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.
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► For further information, please contact

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